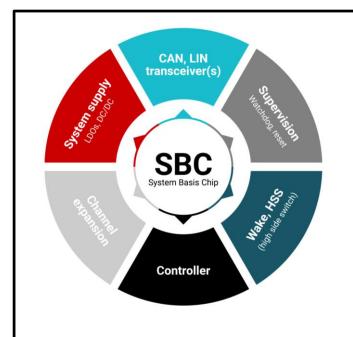


Agenda

Introduction to system basis chips (SBC) Prelude to TCAN24xx Family Car access system overview & challenges Benefits of TCAN24xx in car access systems Summary and Q&A

TI's System Basis Chips (SBC)

Integrated CAN, LIN and voltage supply components in a single package



- Optimized system board space and cost for any applications that need bus communication, power supply, and supervision.
- Saves power with low quiescent current and efficient power conversion features
- Industry tested solutions with full OEM approvals for use

TRX-SBC | Top Sectors with TI Portfolio

Automotive Applications

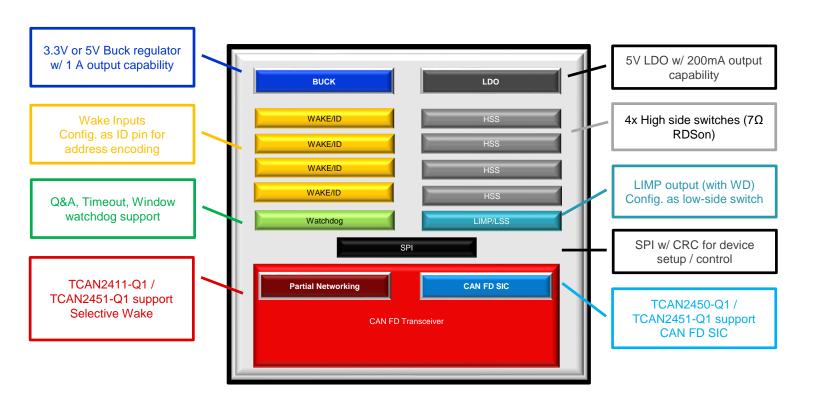
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Advanced Driver Hybrid, Electric, & **Body Electronics &** Indu tions **Assistance Systems Powertrain Systems** Lighting (ADAS) **EE Category EE Category EE Category TOP Sectors** Automotive lighting Wired interface Automotive radar Motor Drives HEV/EV battery management system (BMS) Car access & security Automotive camera Factory automation Heating & Cooling Sensor fusion Appliances Steering wheel column Industrial Transportation Create scalable, flexible systems Design robust powertrain and Deliver advanced and adaptable Deliver advanced and adaptable safety systems for a smooth for enhanced performance and electric systems for any safety systems for a smooth driving experience reliability environment driving experience Functional Safety Manual and FMEDA Balance the need for high bus fault Optimized system for combined bus Combine transceiver, voltage regulators, and other features on a protection and optimized chip size provided communication and power supply single chip

Samples: April 2024

TCAN241x-Q1 / TCAN245x-Q1 (RHB-32/DCP-38)

Power-efficient CAN SBC



Choose 1 **CAN FD CAN PN** CAN FD SIC SIC w/ PN **BUCK** LDO Wake Watchdog

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TCAN24xx-Q1: Power-efficient CAN SBC

CAN FD / CAN FD SIC SBCs w/ integrated Buck regulator and LDO

Common Features

Bus Communication

- ISO11898-2:2016 compliant → CAN FD up to 5Mbps
- ISO11898-2:2023 compliant → CAN FD SIC (optional)

System Supply

- Extended supply voltage operation 5.5 V 28 V
- 3.3V or 5V Buck regulator (Vcc1) with 1A output capability
- 5V LDO (Vcc2) with 200 mA output capability

Control of power consumption

- · Sleep mode with remote wake and 4x local wake inputs
- Partial networking / selective wake (Optional)

Supervision

- Watchdog support (Time-out, Window and Q&A).
- · LIMP output for watchdog and other critical failures

Additional features

- · Wake pins, configurable as ID pins for address encoding
- 4 high-side switches- support up to 100mA and R_{DSON} of 7Ω (typ)
- · Channel expansion- Add more CAN or LIN channels.

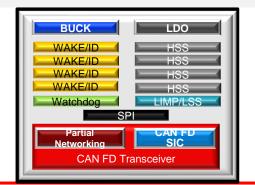
Protection features

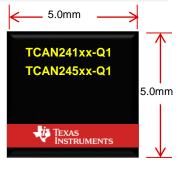
 Failsafe mode, bus fault tolerant up to ±58 V, high ESD, thermal shutdown protection

Small package (32-Pin QFN, 5mm x5mm) with wettable flanks

Key Benefits

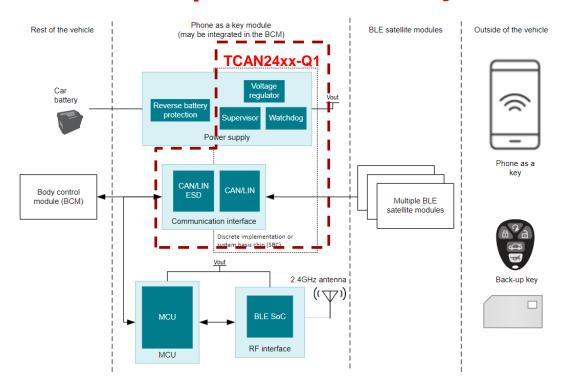
- Quickly upgrade to the latest standard of BUS communication
- Delivers a fixed output voltage, while supporting up to 1A with high efficiency
- Reduces the overall system power consumption
- WD ensures that the processor works correctly
- ID Pins Simplifies the ECU address encoding, in car access







Overview | Car Access System



Notes

- TCAN24xx-Q1 SBC integrates bus communication, power and supervision into a single chip
- Simplifies the system implementation

Overview | Car Access Architecture

Gateway node

<2m Operations

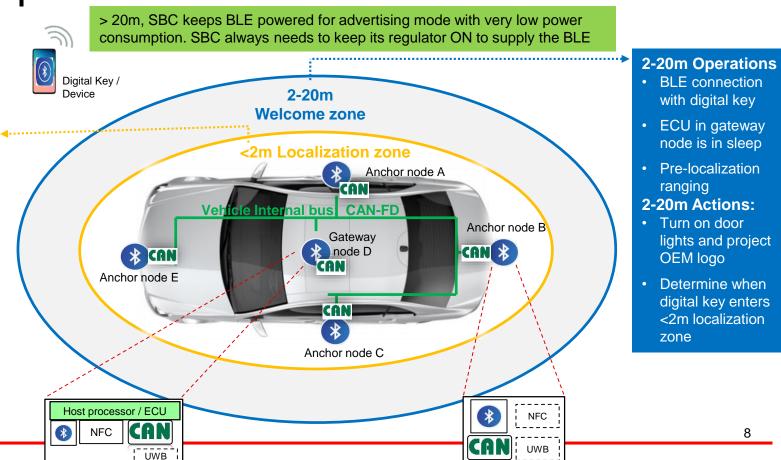
- BLE connection with digital key
- Electronic Control Unit (ECU) in gateway node is active
- Localization using trilateration (e.g. with RSSI, UWB, Bluetooth channe sounding)

<2m Actions:

- Open door if valid digital key is detected is outside the car
- Turn on engine if valid digital key is detected inside the car

Optional

Component

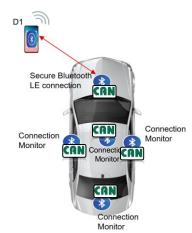


Anchor node

Problem Statement | Need for "seamless" Bluetooth LE connection handover

- Multiple Bluetooth LE nodes on vehicle are advertising (ADV)
- 2. When a device D1 comes in wireless range of vehicle, it connects to one of the vehicle BLE nodes.



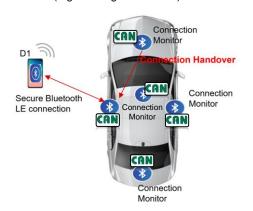


Device D1 may receive ADV from multiple BLE nodes from the same vehicle.

- The device connects to one BLE node.
- However, D1 does not select the optimum BLE vehicle node (e.g. based on RSSI, etc.) to establish connection.

After this initial connection, the device can move away from the BLE anchor node its in connection with.

3a. Move around the vehicle (e.g. walking to the trunk)



3b. Move from outside the vehicle to inside the vehicle

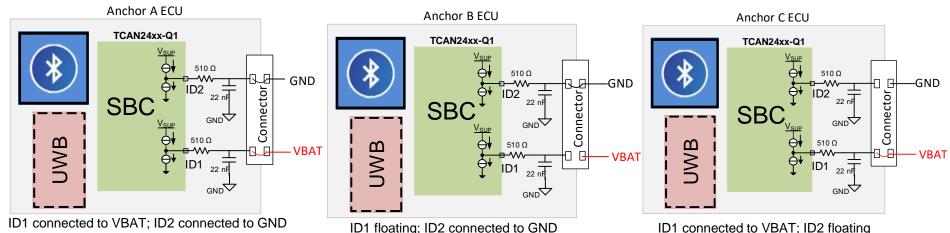


Device D1 can have bad link budget with current BLE node, leading to a disconnection of the BLE link.

- Then D1 scans ADV from vehicle BLE nodes and reconnects; this time with another BLE node.
- This disconnect/reconnect is a "hard" connection handover. It impacts the overall user-experience.
- · Thus, the need for a "seamless" or soft BLE connection handover.
- SBC's <u>CAN module can be turned ON</u> to perform the connection handover to the next node to provide a seamless or soft handover
- SBC's ID-pin encoded address info can be used to perform triangulation



Simple Solution for Address Encoding

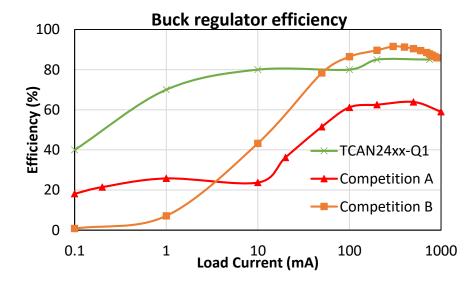


0: GND 1:VBAT F: Floating	ID2	ID1
Anchor A	0	1
Anchor B	0	F
Anchor C	F	1

- TCAN24xx-Q1 provides an easy, simple method to achieve address encoding based on the pin connection
 - Each pin can be connected to either GND, VBAT or floating to encode location
 - Even With 2 ID pins, up to 9 addresses can be encoded
- Together with CAN, address encoding helps with connection handover, triangulation etc

Reducing Battery Power Consumption

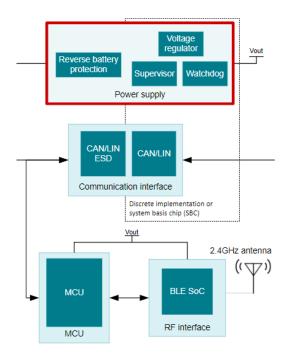
- BLE anchors are always in advertising mode until a connection is established
 - CAN SBC needs to keep BLE powered-on all the time
 - A low quiescent-current Sleep mode, with VCC1 powered, is needed
 - In advertising mode, load on VCC1 is on average < 100 μA
 - Regulator efficiency needs to be high at small load currents



Buck regulators with PFM mode and low quiescent current help keep the total battery current draw from the ECU below 100µA

Supervision

Phone as a key module (may be integrated in the BCM)

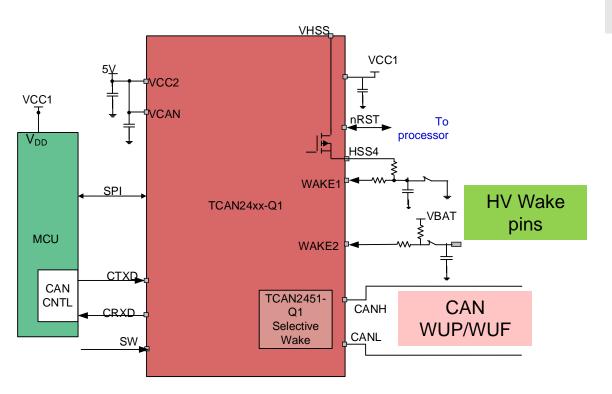


TCAN24xx-Q1 SBC provides power supply supervision and watchdog function

- VCC1 Power Supply Supervision
 - Undervoltage (pre-warning as well as reset)
 - Overvoltage
 - Short-circuit
- VCC2 (for CAN supply)
 - Undervoltage
 - Overvoltage
- VSUP
 - Undervoltage
- Watchdog
 - Low power timeout watchdog
 - Window watchdog
 - Q&A

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Wake Capabilities



SBC can be woken up from lowpower mode by any of the following

- CAN wake-up (WUP)
 - Selective wake-up via frame (WUF) is available with TCAN24x1-Q1 variants
- Wake up via HV pins Wake1-4
 - Wake pin always connected to VBAT/GND (static wake)
 - Cyclic sensing wake via HSS4
- Low voltage wake pin (SW)
- Cyclic wake (internal timer based wakeup)
- · SPI-based if MCU is powered

TCAN241x-Q1 / TCAN245x-Q1

Power-efficient CAN SBC for Car Access System

Features

Key features for Car access system

- Integrated 1A Buck regulator → Reduce system batter power consumption.
- ID Pins → enables address encoding for fast handover.
- Supervision features → Helps with functional safety implementation

Discovery questions

A few things to consider

- Do you need power supply in addition to the bus communication?
- How will you manage power?
- How are you implementing address encoding?
- Do you need to drive additional loads with High side switches?

Getting started

You can start evaluating this device leveraging the following:

Content type	Content title	Link to content or more details
Product folder	An overview of the devices features and access to the datasheet.	Coming Soon – April 2024! https://www.ti.com/product/TCAN2451-Q1 https://www.ti.com/product/TCAN2450-Q1
E2E Forum	TI's forum to submit any inquiry or technical questions on TCAN24xx-Q1 devices	https://e2e.ti.com/support/interface- group/interface/f/interface-forum
Technical blog	An overview of system basis chips, and their integrated power control capabilities.	https://www.ti.com/lit/pdf/sszt469
System basis chips Portal	A web overview of all SBCs	System basis chips (SBCs) TI.com



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